



Title of Change:	eFuse devices NIS5132MN4TXG & NIS5135MN4TXG tested to Huawei's special requirements		
Proposed first ship date:	25 August 2016 or earlier after customer approval.		
Contact information:	Contact your local ON Semiconductor Sales Office or <ed.pope@onsemi.com>		
Samples:	Contact your local ON Semiconductor Sales Office		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <ed.pope@onsemi.com>.		
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.		
Change Part Identification:	Affected product shall be with part numbers: NIS5132MN4TXG, marked 324, date code 1634 (alpha code RFH) NIS5134MN4TXG, marked 354, date code 1634 (Alpha code RFH)		
Change category:	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input checked="" type="checkbox"/> Test Change <input type="checkbox"/> Other _____		
Change Sub-Category(s): <div style="display: flex; flex-wrap: wrap;"> <div style="width: 33%;"><input type="checkbox"/> Manufacturing Site Change/Addition</div> <div style="width: 33%;"><input type="checkbox"/> Material Change</div> <div style="width: 33%;"><input type="checkbox"/> Datasheet/Product Doc change</div> <div style="width: 33%;"><input type="checkbox"/> Manufacturing Process Change</div> <div style="width: 33%;"><input type="checkbox"/> Product specific change</div> <div style="width: 33%;"><input type="checkbox"/> Shipping/Packaging/Marking</div> <div style="width: 33%;"><input checked="" type="checkbox"/> Other: <u>ATE Test</u></div> </div>			
Sites Affected: <input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Seremban, Malaysia <input type="checkbox"/> External Foundry/Subcon site(s)			
Description and Purpose: The standard eFuse devices NIS5132MN1TXG & NIS5135MN1TXG will have a Huawei special ATE test sequence that will include special ON/OFF test sequence. All other ATE test shall guarantee the performance of the NIS5132MN1TXG & NIS5135MN1TXG Data Sheet. There will be no change to the BOM, wafer source, mfg process or mfg site. The Huawei new OPN designation shall be NIS5132MN4TXG and NIS5135MN4TXG. Since there are no changes to the BOM, wafer, die, or mfg process, no new or special qualification is required for the NIS5132MN4TXG & NIS5135MN4TXG.			
Electrical Characteristic Summary: Electrical characteristics per the standard NIS5132MN1TXG and NIS5135MN1TXG data sheets are not impacted.			
List of affected Standard Parts:			
Part Number		Qualification Vehicle	
NIS5132MN4TXG		NIS5132MN1TXG	
NIS5135MN4TXG		NIS5132MN1TXG family qual for NIS5135MN1TXG	